Title: SHC-Sample/Hold

Component List:
- L1: LH1206B900R
- C1: 2.2uF
- C2: 2.2uF
- C3: 0.1uF
- C4: 0.1uF
- C5: 0.1uF
- C6: 22pF
- R1: 49.9
- R2: 124
- R3: 300
- R4: 300
- R5: 100
- R6: 49.9
- R7: 0
- R8: 0
- U1: OPA615ID

Connections:
- IN -> C1
- OUT -> GND
- E_Out -> GND
- GND

Note: The diagram includes various resistors and capacitors with specific values, as well as connections for power and ground.
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